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From: Rose A. Keagy  
Texas Instruments Incorporated  
Facsimile: 972-917-4418  
Phone: 972-917-4761

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

TI-31484

Andrew Marshall

Art Unit: 2815

Serial No.: 10/007,332

Examiner: Warren, M.E.

Filed: 8-Nov-01

Conf. No.: 3238

For: Thermal Coupling of Matched SOI Device Bodies

CERTIFICATION OF FACSIMILE TRANSMISSION

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Robin E. Bamum

August 30, 2004  
Date

FACSIMILE COVER SHEET

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<input type="checkbox"/> CONTINUATION APPN (# Pages)	
<input type="checkbox"/> DIVISIONAL APPN	
<b>NAME OF INVENTOR(S):</b> Andrew Marshall	
<b>TITLE OF INVENTION:</b> Thermal Coupling of Matched SOI Device Bodies	
<b>TI FILE NO.:</b> TI-31484	<b>DEPOSIT ACCT. NO.:</b> 20-0668
<b>FAXED:</b> 8/30/04 <b>DUE:</b> 9/26/04 <b>ATTY/SEC'Y:</b> RAK/reb	<b>RECEIPT DATE &amp; SERIAL NO.:</b> <b>Serial No.:</b> 10/007,332 <b>Filing Date:</b> November 8, 2001

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Texas Instruments Incorporated  
PO Box 655474, M/S 3999  
Dallas, TX 75265

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: Andrew Marshall

Docket No.: TI-31484

Serial No.: 10/007,332

Art Unit: 2815

Filed: 11/08/01

Examiner: Warren, M. E.

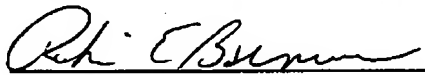
Title: Thermal Coupling of Matched SOI Device Bodies

REPLY UNDER 37 C.F.R. §1.116 – EXPEDITED PROCEDURE  
TECHNOLOGY CENTER 2800

August 30, 2004

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

CERTIFICATION OF FAX TRANSMITTAL  
I hereby certify that the above correspondence is being facsimile  
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Robin E. Barnum

Dear Sir:

In response to the Office Action, dated 07/26/2004, in the above-identified patent application, please make the following amendments. They are respectfully submitted as a full and complete response to that Action. Charge any required fees to the deposit account of Texas Instruments Incorporated, Account No. 20-0668.